

Dual N-channel MOSFET

ELM14842AA-N

■ General description

ELM14842AA-N uses advanced trench technology to provide excellent R_{d(on)} and low gate charge.

■ Features

- V_{ds}=30V
- I_d=7.5A (V_{gs}=10V)
- R_{d(on)} < 22mΩ (V_{gs}=10V)
- R_{d(on)} < 35mΩ (V_{gs}=4.5V)

■ Maximum absolute ratings

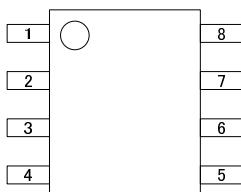
Parameter	Symbol	Limit	Unit	Note
Drain-source voltage	V _{ds}	30	V	
Gate-source voltage	V _{gs}	±20	V	
Continuous drain current	I _d	7.5	A	1
		6.4		
Pulsed drain current	I _{dm}	30	A	2
Power dissipation	P _d	2.00	W	
		1.44		
Junction and storage temperature range	T _j , T _{stg}	-55 to 150	°C	

■ Thermal characteristics

Parameter		Symbol	Typ.	Max.	Unit	Note
Maximum junction-to-ambient	t≤10s	R _{θja}	50.0	62.5	°C/W	1
Maximum junction-to-ambient	Steady-state		82.0	110.0	°C/W	
Maximum junction-to-lead	Steady-state	R _{θjl}	41.0	50.0	°C/W	3

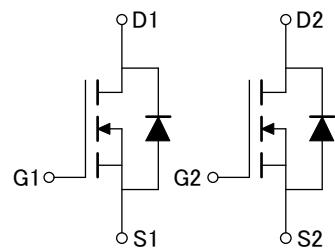
■ Pin configuration

SOP-8 (TOP VIEW)



Pin No.	Pin name
1	SOURCE2
2	GATE2
3	SOURCE1
4	GATE1
5	DRAIN1
6	DRAIN1
7	DRAIN2
8	DRAIN2

■ Circuit



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■ Electrical characteristics

$T_a=25^\circ C$

Parameter	Symbol	Condition		Min.	Typ.	Max.	Unit
STATIC PARAMETERS							
Drain-source breakdown voltage	BVdss	$I_d=250\mu A$, $V_{gs}=0V$		30			V
Zero gate voltage drain current	Idss	$V_{ds}=30V$			0.004	1.000	μA
		$V_{gs}=0V$	$T_j=55^\circ C$			5.000	
Gate-body leakage current	Igss	$V_{ds}=0V$, $V_{gs}=\pm 20V$				100	nA
Gate threshold voltage	Vgs(th)	$V_{ds}=V_{gs}$, $I_d=250\mu A$		1.00	1.65	3.00	V
On state drain current	$I_d(on)$	$V_{gs}=4.5V$, $V_{ds}=5V$		20			A
Static drain-source on-resistance	Rds(on)	$V_{gs}=10V$			18	22	$m\Omega$
		$I_d=7.5A$	$T_j=125^\circ C$		26	31	
		$V_{gs}=4.5V$, $I_d=5A$			28	35	
Forward transconductance	Gfs	$V_{ds}=5V$, $I_d=7.5A$		10	24		S
Diode forward voltage	Vsd	$I_s=1A$, $V_{gs}=0V$			0.77	1.00	V
Max. body-diode continuous current	Is					4.3	A
DYNAMIC PARAMETERS							
Input capacitance	Ciss	$V_{gs}=0V$, $V_{ds}=15V$, $f=1MHz$			621	820	pF
Output capacitance	Coss				118		pF
Reverse transfer capacitance	Crss				85		pF
Gate resistance	Rg	$V_{gs}=0V$, $V_{ds}=0V$, $f=1MHz$			0.8	1.5	Ω
SWITCHING PARAMETERS							
Total gate charge (10V)	Qg	$V_{gs}=10V$, $V_{ds}=15V$, $I_d=7.5A$			12.0	17.0	nC
Total gate charge (4.5V)	Qg				6.0	8.0	nC
Gate-source charge	Qgs				2.1		nC
Gate-drain charge	Qgd				3.0		nC
Turn-on delay time	td(on)	$V_{gs}=10V$, $V_{ds}=15V$			4.5	6.5	ns
Turn-on rise time	tr				3.1	5.0	ns
Turn-off delay time	td(off)		$R_L=2\Omega$, $R_{gen}=3\Omega$		15.1	23.0	ns
Turn-off fall time	tf				2.7	5.0	ns
Body diode reverse recovery time	trr	$I_f=7.5A$, $dl/dt=100A/\mu s$			15.5	20.0	ns
Body diode reverse recovery charge	Qrr	$I_f=7.5A$, $dl/dt=100A/\mu s$			7.1	10.0	nC

NOTE :

- The value of $R_{\theta ja}$ is measured with the device mounted on 1in² FR-4 board of 2oz. Copper, in still air environment with $T_a=25^\circ C$. The value in any given applications depends on the user's specific board design, The current rating is based on the $t \leq 10s$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The $R_{\theta ja}$ is the sum of the thermal impedance from junction to lead $R_{\theta jl}$ and lead to ambient.
- The static characteristics in Figures 1 to 6 are obtained using 80 μs pulses, duty cycle 0.5%max.
- These tests are performed with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_a=25^\circ C$. The SOA curve provides a single pulse rating.

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■ Typical electrical and thermal characteristics

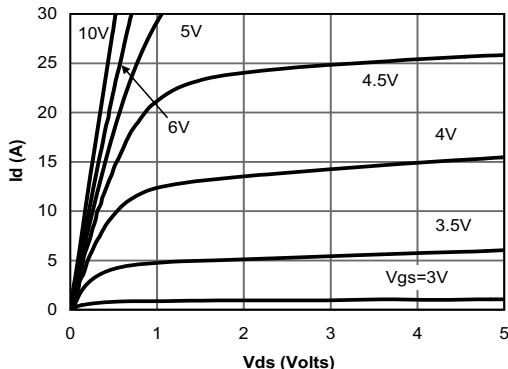


Fig 1: On-Region Characteristics

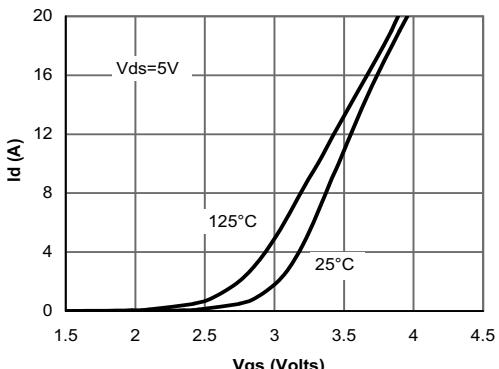


Figure 2: Transfer Characteristics

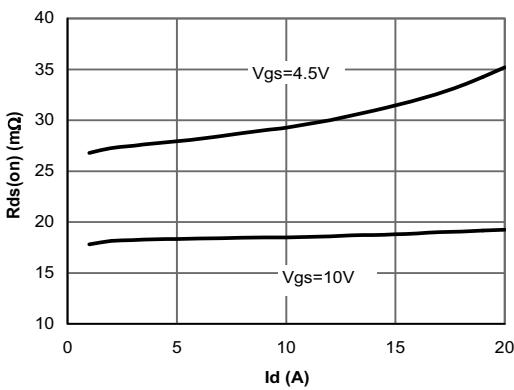


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

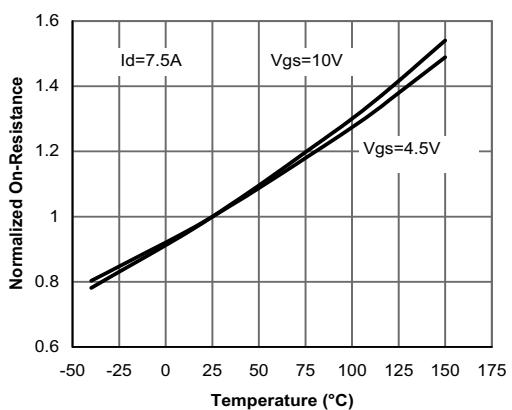


Figure 4: On-Resistance vs. Junction Temperature

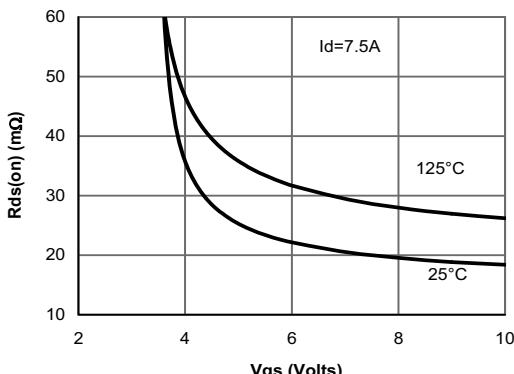


Figure 5: On-Resistance vs. Gate-Source Voltage

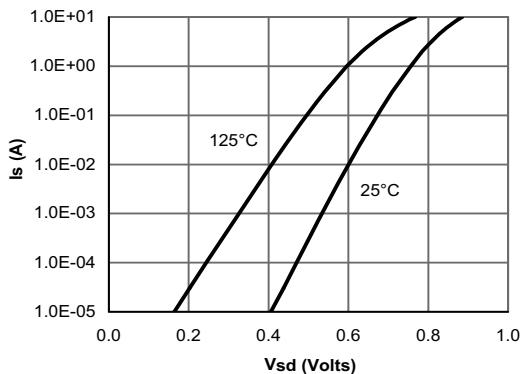


Figure 6: Body-Diode Characteristics

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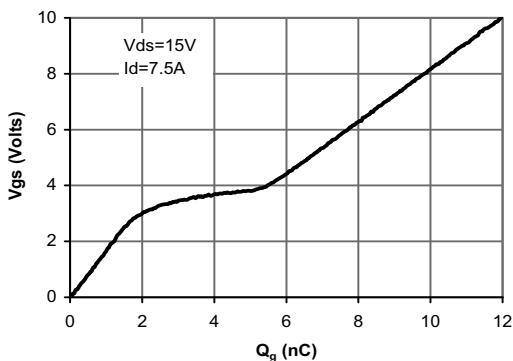


Figure 7: Gate-Charge Characteristics

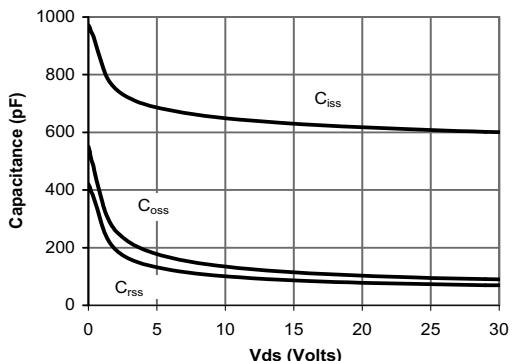


Figure 8: Capacitance Characteristics

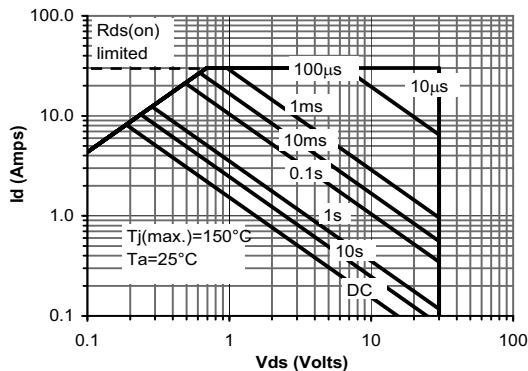


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

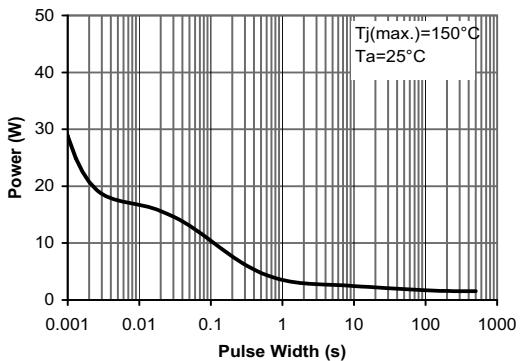


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

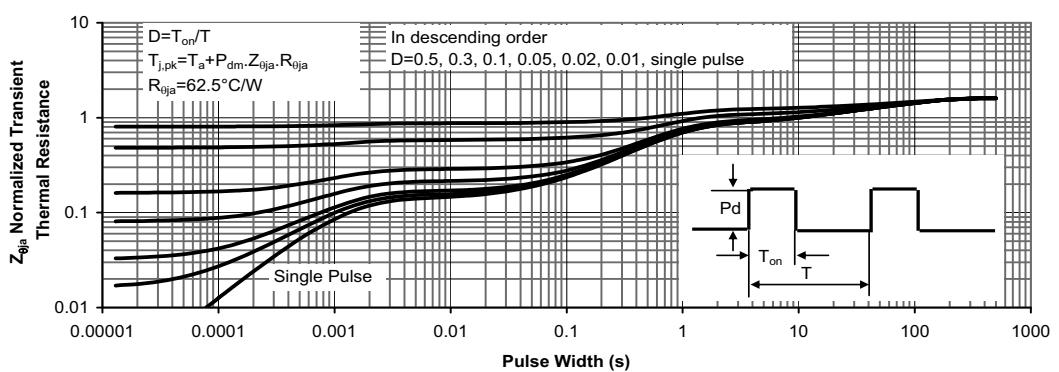


Figure 11: Normalized Maximum Transient Thermal Impedance